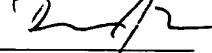


AMENDMENT TRANSMITTAL LETTER				Docket No. TESSERA 3.0-109 CIP DIV	
Application No. 09/776,356		Filing Date February 2, 2001		Examiner D. Graybill	Art Unit 2827
Applicant(s): Young-Gon Kim, Belgacem Haba, and Vernon Solberg					
Invention: STACKED MICROELECTRONIC ASSEMBLY AND METHOD THEREFOR					
TO THE COMMISSIONER FOR PATENTS					
Transmitted herewith is an amendment in the above-identified application.					
The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
Total Claims	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
33	- 20 =	13	x 18.00	234.00	
Independent Claims	4	- 4 =	x	0.00	
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					234.00
<input checked="" type="checkbox"/> Large Entity <input type="checkbox"/> Small Entity <input type="checkbox"/> No additional fee is required for this amendment. <input checked="" type="checkbox"/> Please charge Deposit Account No. <u>12-1095</u> in the amount of \$ <u>234.00</u> . A duplicate copy of this sheet is enclosed. <input type="checkbox"/> A check in the amount of \$ _____ to cover the filing fee is enclosed. <input type="checkbox"/> Payment by credit card. Form PTO-2038 is attached. <input checked="" type="checkbox"/> The Commissioner is hereby authorized to charge and credit Deposit Account No. <u>12-1095</u> as described below. A duplicate copy of this sheet is enclosed. <input checked="" type="checkbox"/> Credit any overpayment. <input checked="" type="checkbox"/> Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.					
Dated: <u>March 12, 2003</u>					
Marcus J. Millet Attorney Reg. No.: 28,241					
LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP 600 South Avenue West Westfield, New Jersey 07090 (908) 654-5000					
I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail, in an envelope addressed to: Commissioner for Patents, Washington, DC 20231, on the date shown below. Dated: March 12, 2003 Signature:  <p>419516_1.DOC</p>					



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Dated: March 12, 2003

Signature: 
(Marcus J. Miller)

Docket No.: TESSERA 3.0-109 CIP DIV
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of :
Kim et al :
Application No.: 09/776,356 : Group Art Unit: 2827
Filed: February 2, 2001 : Examiner: D. Graybill
For: STACKED MICROELECTRONIC ASSEMBLY :
AND METHOD THEREFOR :
:

Commissioner for Patents
Washington, DC 20231

AMENDMENT

Dear Sir:

In response to the Official Action mailed September 12, 2002, applicant submits the following amendments and remarks.

IN THE CLAIMS

1. (AMENDED) A method of making a stacked microelectronic assembly comprising the steps of:

I. providing a flexible substrate having a plurality of attachment sites, said flexible substrate including a first surface and a second surface and having a plurality of electrically conductive terminals accessible at at least one of said first and second surfaces; test contacts accessible at at least one of said first and second surfaces; and wiring connected to said terminals and test contacts, said wiring including flexible leads extending to said attachment sites;

II. assembling a plurality of microelectronic elements to said attachment sites;

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